

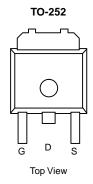
P-Channel 40 V (D-S) MOSFET

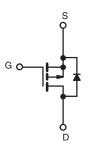
| PRODUCT SUMMARY | | | | | |
|--|--------|--|--|--|--|
| V _{DS} (V) | -40 | | | | |
| $R_{DS(on)}$ (Ω) at V_{GS} = -10 V | 0.012 | | | | |
| $R_{DS(on)}$ (Ω) at $V_{GS} = -4.5 \text{ V}$ | 0.015 | | | | |
| I _D (A) | -50 | | | | |
| Configuration | Single | | | | |

FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- \bullet 100 % R_g and UIS tested







P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS | (T _C = 25 °C, unles | s otherwise noted |) | | |
|--|-------------------------------------|-----------------------------------|-------------|----|--|
| PARAMETER | SYMBOL | LIMIT | UNIT | | |
| Drain-Source Voltage | | V _{DS} | -40 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | V | |
| Continuous Drain Current | T _C = 25 °C ^a | 1 | -50 | | |
| | T _C = 125 °C | I _D | -39 | | |
| Continuous Source Current (Diode Conduction | I _S | -50 | Α | | |
| Pulsed Drain Current ^b | I _{DM} | -200 | | | |
| Single Pulse Avalanche Current | L = 0.1 mH | | -40 | | |
| Single Pulse Avalanche Energy | L = 0.1 IIII | E _{AS} | 80 | mJ | |
| | T _A = 25 °C | | 3 | | |
| Maximum Power Dissipation ^b | T _C = 25 °C | P_{D} | 136 | W | |
| | T _C = 125 °C | | 45 | | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | -55 to +175 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|----------------------------|-------------|------------|-------|-------|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | |
| Junction-to-Ambient | PCB Mount c | R_{thJA} | 50 | °C/W | |
| Junction-to-Case (Drain) | | R_{thJC} | 1.1 | C/ VV | |

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.



| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT | |
|---|---------------------|---|--|------|-------|-------|------|--|
| Static | - | | | | | l | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$ | | -40 | - | - | ., | |
| Gate-Source Threshold Voltage | V _{GS(th)} | V _{DS} = | V _{DS} = V _{GS} , I _D = -250 μA | | - | -2.5 | V | |
| Gate-Source Leakage | I _{GSS} | V _{DS} = | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | - | ± 100 | nA | |
| | | V _{GS} = 0 V | V _{DS} = -40 V | - | - | -1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{GS} = 0 V | V _{DS} = -40 V, T _J = 125 °C | - | - | -50 | μA | |
| | | V _{GS} = 0 V | V _{DS} = -40 V, T _J = 175 °C | - | - | -150 | | |
| On-State Drain Current ^a | I _{D(on)} | V _{GS} = -10 V | V _{DS} ≤ -5 V | -50 | - | - | Α | |
| | | V _{GS} = -10 V | I _D = -17 A | - | 0.012 | - | Ω | |
| Dunin Course On Chata Basistanas | | V _{GS} = -10 V | I _D = -50 A, T _J = 125 °C | - | 0.017 | - | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = -10 V | I _D = -50 A, T _J = 175 °C | - | 0.020 | - | | |
| | | V _{GS} = -4.5 V | I _D = -14 A | - | 0.015 | - | | |
| Forward Transconductance ^a | 9fs | V _{DS} = -15 V, I _D = -17 A | | - | 61 | - | S | |
| Dynamic ^b | | | | | | | | |
| Input Capacitance | C _{iss} | | | - | 2872 | 3950 | pF | |
| Output Capacitance | Coss | $V_{GS} = 0 V$ | V _{DS} = -25 V, f = 1 MHz | - 50 | 508 | 635 | | |
| Reverse Transfer Capacitance | C _{rss} | | | = | 352 | 440 | | |
| Total Gate Charge ^c | Qg | | | - | 60 | 80 | | |
| Gate-Source Charge ^c | Q _{gs} | V _{GS} = -10 V | $V_{DS} = -30 \text{ V}, I_D = -50 \text{ A}$ | - | 5.7 | 8.6 | nC | |
| Gate-Drain Charge ^c | Q _{gd} | | | - | 14.7 | 22 | | |
| Gate Resistance | R _g | f = 1 MHz | | 1.5 | 3 | 4.5 | Ω | |
| Turn-On Delay Time ^c | t _{d(on)} | V_{DD} = -20 V, R_L = 0.4 Ω I_D \cong -50 A, V_{GEN} = -10 V, R_g = 1 Ω | | - | 10 | 15 | ns | |
| Rise Time ^c | t _r | | | - | 12 | 18 | | |
| Turn-Off Delay Time ^c | t _{d(off)} | | | 1 | 40 | 60 | | |
| Fall Time ^c | t _f | | | - | 16 | 24 | | |
| Source-Drain Diode Ratings and Chara | acteristics b | | | | | | | |
| Pulsed Current ^a | I _{SM} | | | - | - | -200 | Α | |
| Forward Voltage | V_{SD} | I _F = -50 A, V _{GS} = 0 V | | - | -1 | -1.5 | V | |

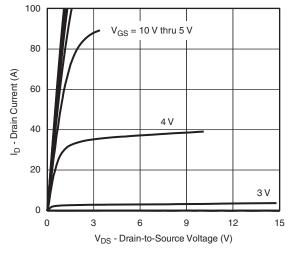
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

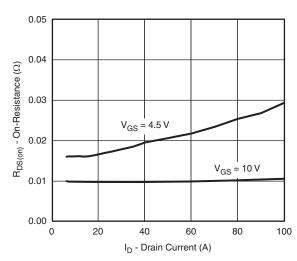
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



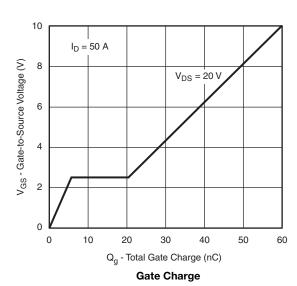
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

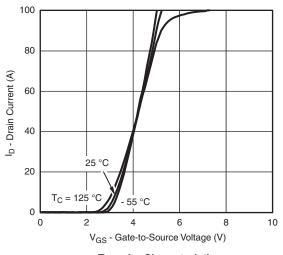


Output Characteristics

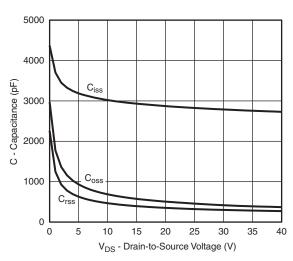


On-Resistance vs. Drain Current

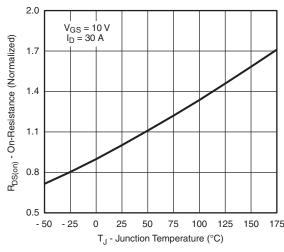




Transfer Characteristics



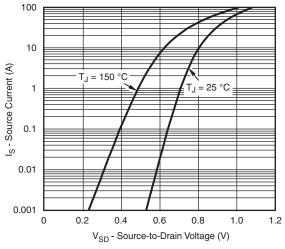
Capacitance

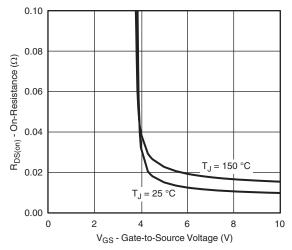


On-Resistance vs. Junction Temperature



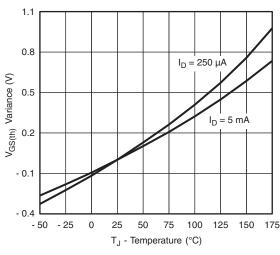
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

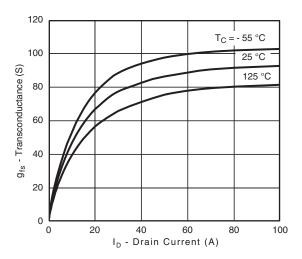




Source Drain Diode Forward Voltage

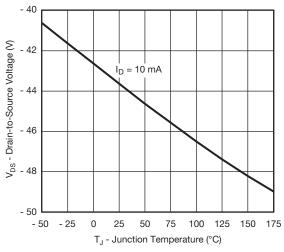
On-Resistance vs. Gate-to Source Voltage





Threshold Voltage

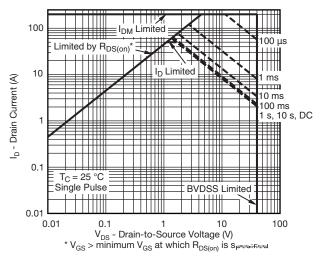
Transconductance



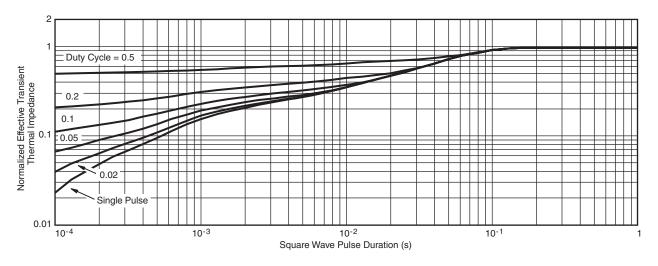
Drain Source Breakdown vs. Junction Temperature



TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

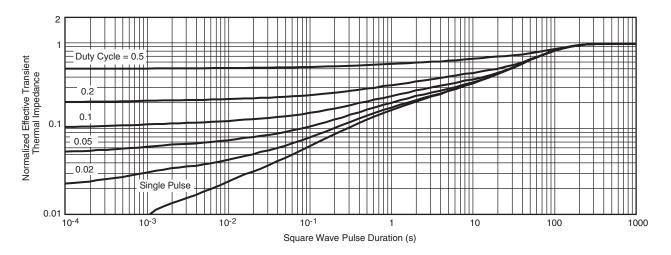


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case





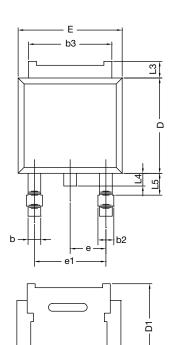
Normalized Thermal Transient Impedance, Junction-to-Ambient

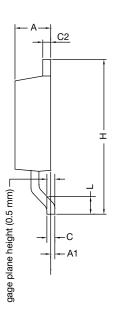
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-252AA Case Outline





| | MILLIN | METERS | INC | HES | | |
|-----------|---------------------------------|--------|-----------|-------|--|--|
| DIM. | MIN. | MAX. | MIN. | MAX. | | |
| Α | 2.18 | 2.38 | 0.086 | 0.094 | | |
| A1 | - | 0.127 | - | 0.005 | | |
| b | 0.64 | 0.88 | 0.025 | 0.035 | | |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 | | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | | |
| С | 0.46 | 0.61 | 0.018 | 0.024 | | |
| C2 | 0.46 | 0.89 | 0.018 | 0.035 | | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | | |
| D1 | 4.10 | - | 0.161 | - | | |
| Е | 6.35 | 6.73 | 0.250 | 0.265 | | |
| E1 | 4.32 | - | 0.170 | - | | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | | |
| е | 2.28 | BSC | 0.090 | BSC | | |
| e1 | 4.56 | BSC | 0.180 BSC | | | |
| L | 1.40 | 1.78 | 0.055 | 0.070 | | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 | | |
| L4 | - | 1.02 | - | 0.040 | | |
| L5 | 1.01 | 1.52 | 0.040 | 0.060 | | |
| ECN: T13- | ECN: T13-0592-Rev. A, 02-Sep-13 | | | | | |

ECN: T13-0 DWG: 6019

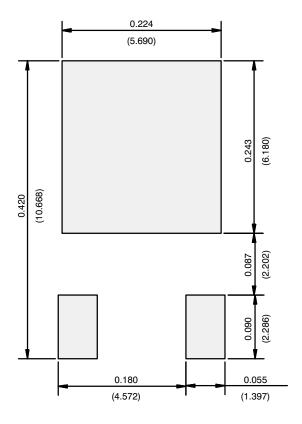
Note

• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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